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Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

#### Details

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	I <sup>2</sup> C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	25
Program Memory Size	7KB (4K x 14)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	192 x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 11x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SOIC (0.295", 7.50mm Width)
Supplier Device Package	28-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lf723-i-so

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Page
Bank 2											
100h <sup>(2)</sup>	INDF	Addressing	this location	uses conten	ts of FSR to a	ddress data	memory (not	a physical re	gister)	xxxx xxxx	29,37
101h	TMR0	Timer0 Mod	ule Register							xxxx xxxx	105,37
102h <sup>(2)</sup>	PCL	Program Co	unter's (PC)	Least Signif	icant Byte					0000 0000	28,37
103h <sup>(2)</sup>	STATUS	IRP	IRP RP1 RP0 TO PD Z DC C								25,37
104h <sup>(2)</sup>	FSR	Indirect Data	a Memory Ac	dress Point	er					xxxx xxxx	29,37
105h	_	Unimplemen	nted							_	_
106h	_	Unimplemen	nted							_	_
107h	—	Unimplemen	nted								_
108h	CPSCON0	CPSON	_	_	_	CPSRNG1	CPSRNG0	CPSOUT	TOXCS	0 0000	126,38
109h	CPSCON1	—	_	_	_	CPSCH3	CPSCH2	CPSCH1	CPSCH0	0000	127,38
10Ah <sup>(1, 2)</sup>	PCLATH	—	_	_	Write Buffer	for the upper	5 bits of the F	Program Cou	nter	0 0000	28,37
10Bh <sup>(2)</sup>	INTCON	GIE	PEIE	TOIE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	44,37
10Ch	PMDATL	Program Me	mory Read	Data Registe	er Low Byte					XXXX XXXX	181,38
10Dh	PMADRL	Program Me	mory Read	Address Reg	gister Low Byt	е				XXXX XXXX	181,38
10Eh	PMDATH	—	_	Program Me	emory Read D	Data Register	High Byte			xx xxxx	181,38
10Fh	PMADRH	—	—	—	Program Me	mory Read A	ddress Regis	ter High Byte	1	x xxxx	181,38
Bank 3											
180h <sup>(2)</sup>	INDF	Addressing	this location	uses conten	ts of FSR to a	ddress data	memory (not	a physical re	gister)	XXXX XXXX	29,37
181h	OPTION_REG	RBPU	INTEDG	TOCS	T0SE	PSA	PS2	PS1	PS0	1111 1111	26,37
182h <sup>(2)</sup>	PCL	Program Co	unter (PC) L	east Signific	ant Byte					0000 0000	28,37
183h <sup>(2)</sup>	STATUS	IRP	RP1	RP0	TO	PD	Z	DC	С	0001 1xxx	25,37
184h <sup>(2)</sup>	FSR	Indirect Data	a Memory Ac	dress Point	er					XXXX XXXX	29,37
185h	ANSELA	—	_	ANSA5	ANSA4	ANSA3	ANSA2	ANSA1	ANSA0	11 1111	52,38
186h	ANSELB		_	ANSB5	ANSB4	ANSB3	ANSB2	ANSB1	ANSB0	11 1111	61,38
187h	—	Unimplemen	nted								_
188h	ANSELD	ANSD7	ANSD6	ANSD5	ANSD4	ANSD3	ANSD2	ANSD1	ANSD0	1111 1111	78,38
189h <sup>(3)</sup>	ANSELE	—	_	_	—	—	ANSE2	ANSE1	ANSE0	111	82,38
18Ah <sup>(1, 2)</sup>	PCLATH	—	_	_	Write Buffer	for the upper	5 bits of the F	Program Cou	nter	0 0000	28,37
18Bh <sup>(2)</sup>	INTCON	GIE	PEIE	TOIE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	44,37
18Ch	PMCON1	Reserved — — — — — RD							RD	10	182,38
18Dh	—	Unimplemented								-	-
18Eh	—	Unimplemen	Unimplemented							-	-
18Fh	—	Unimplemen	nted							_	_

#### **TABLE 2-1:** PIC16(L)F722/3/4/6/7 SPECIAL FUNCTION REGISTER SUMMARY (CONTINUED)

x = unknown, u = unchanged, q = value depends on condition, - = unimplemented, read as '0', r = reserved. Shaded locations are unimplemented, read as '0'. Legend:

The upper byte of the program counter is not directly accessible. PCLATH is a holding register for the PC<12:8>, whose contents are transferred to the upper byte of the program counter. Note 1:

These registers can be addressed from any bank. 2:

These registers/bits are not implemented on PIC16F722/723/726/PIC16LF722/723/726 devices, read as '0'. Accessible only when SSPM<3:0> = 1001. Accessible only when SSPM<3:0>  $\neq$  1001. This bit is always '1' as RE3 is input-only. 3:

4:

5:

6:

#### 4.1 Operation

Interrupts are disabled upon any device Reset. They are enabled by setting the following bits:

- GIE bit of the INTCON register
- Interrupt Enable bit(s) for the specific interrupt event(s)
- PEIE bit of the INTCON register (if the Interrupt Enable bit of the interrupt event is contained in the PIE1 and PIE2 registers)

The INTCON, PIR1 and PIR2 registers record individual interrupts via Interrupt Flag bits. Interrupt Flag bits will be set, regardless of the status of the GIE, PEIE and individual Interrupt Enable bits.

The following events happen when an interrupt event occurs while the GIE bit is set:

- Current prefetched instruction is flushed
- · GIE bit is cleared
- Current Program Counter (PC) is pushed onto the stack
- · PC is loaded with the interrupt vector 0004h

The ISR determines the source of the interrupt by polling the Interrupt Flag bits. The Interrupt Flag bits must be cleared before exiting the ISR to avoid repeated interrupts. Because the GIE bit is cleared, any



FIGURE 4-2: INT PIN INTERRUPT TIMING

interrupt that occurs while executing the ISR will be recorded through its Interrupt Flag, but will not cause the processor to redirect to the interrupt vector.

The  ${\tt RETFIE}$  instruction exits the ISR by popping the previous address from the stack and setting the GIE bit.

For additional information on a specific interrupt's operation, refer to its peripheral chapter.

- Note 1: Individual Interrupt Flag bits are set, regardless of the state of any other enable bits.
  - 2: All interrupts will be ignored while the GIE bit is cleared. Any interrupt occurring while the GIE bit is clear will be serviced when the GIE bit is set again.

#### 4.2 Interrupt Latency

Interrupt latency is defined as the time from when the interrupt event occurs to the time code execution at the interrupt vector begins. The latency for synchronous interrupts is three instruction cycles. For asynchronous interrupts, the latency is three to four instruction cycles, depending on when the interrupt occurs. See Figure 4-2 for timing details.

- 4: For minimum width of INT pulse, refer to AC specifications in Section 23.0 "Electrical Specifications".
- **5:** INTF is enabled to be set any time during the Q4-Q1 cycles.

3: CLKOUT is available only in INTOSC and RC Oscillator modes.

#### 4.3 Interrupts During Sleep

Some interrupts can be used to wake from Sleep. To wake from Sleep, the peripheral must be able to operate without the system clock. The interrupt source must have the appropriate Interrupt Enable bit(s) set prior to entering Sleep.

On waking from Sleep, if the GIE bit is also set, the processor will branch to the interrupt vector. Otherwise, the processor will continue executing instructions after the SLEEP instruction. The instruction directly after the SLEEP instruction will always be executed before branching to the ISR. Refer to the **Section 19.0** "**Power-Down Mode (Sleep)**" for more details.

#### 4.4 INT Pin

The external interrupt, INT pin, causes an asynchronous, edge-triggered interrupt. The INTEDG bit of the OPTION register determines on which edge the interrupt will occur. When the INTEDG bit is set, the rising edge will cause the interrupt. When the INTEDG bit is clear, the falling edge will cause the interrupt. The INTF bit of the INTCON register will be set when a valid edge appears on the INT pin. If the GIE and INTE bits are also set, the processor will redirect program execution to the interrupt vector. This interrupt is disabled by clearing the INTE bit of the INTCON register.

#### 4.5 Context Saving

When an interrupt occurs, only the return PC value is saved to the stack. If the ISR modifies or uses an instruction that modifies key registers, their values must be saved at the beginning of the ISR and restored when the ISR completes. This prevents instructions following the ISR from using invalid data. Examples of key registers include the W, STATUS, FSR and PCLATH registers.



The code shown in Example 4-1 can be used to do the following.

- Save the W register
- Save the STATUS register
- Save the PCLATH register
- Execute the ISR program
- Restore the PCLATH register
- Restore the STATUS register
- Restore the W register

Since most instructions modify the W register, it must be saved immediately upon entering the ISR. The SWAPF instruction is used when saving and restoring the W and STATUS registers because it will not affect any bits in the STATUS register. It is useful to place  $W_{TEMP}$  in shared memory because the ISR cannot predict which bank will be selected when the interrupt occurs.

The processor will branch to the interrupt vector by loading the PC with 0004h. The PCLATH register will remain unchanged. This requires the ISR to ensure that the PCLATH register is set properly before using an instruction that causes PCLATH to be loaded into the PC. See **Section 2.3 "PCL and PCLATH"** for details on PC operation.



#### TABLE 6-1: SUMMARY OF REGISTERS ASSOCIATED WITH PORTA

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
ADCON0	-	—	CHS3	CHS2	CHS1	CHS0	GO/DONE	ADON	0000 0000	0000 0000
ADCON1		ADCS2	ADCS1	ADCS0	—	—	ADREF1	ADREF0	-00000	-00000
ANSELA	-	—	ANSA5	ANSA4	ANSA3	ANSA2	ANSA1	ANSA0	11 1111	11 1111
APFCON	_	_	_	_	_	_	SSSEL	CCP2SEL	00	00
CPSCON0	CPSON	_	_	_	CPSRNG1	CPSRNG0	CPSOUT	TOXCS	0 0000	0 0000
CPSCON1	_	_	_	_	CPSCH3	CPSCH2	CPSCH1	CPSCH0	0000	0000
CONFIG2 <sup>(1)</sup>	_	_	VCAPEN1	VCAPEN0	—	_	_	-	-	—
OPTION_REG	RBPU	INTEDG	TOCS	T0SE	PSA	PS2	PS1	PS0	1111 1111	1111 1111
PORTA	RA7	RA6	RA5	RA4	RA3	RA2	RA1	RA0	xxxx xxxx	xxxx xxxx
SSPCON	WCOL	SSPOV	SSPEN	CKP	SSPM3	SSPM2	SSPM1	SSPM0	0000 0000	0000 0000
TRISA	TRISA7	TRISA6	TRISA5	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	1111 1111	1111 1111

 $\label{eq:Legend: x = unknown, u = unchanged, - = unimplemented locations read as `0'. Shaded cells are not used by PORTA.$ 

Note 1: PIC16F72X only.

#### FIGURE 6-12: BLOCK DIAGRAM OF RB7



#### 9.1.5 INTERRUPTS

The ADC module allows for the ability to generate an interrupt upon completion of an Analog-to-Digital conversion. The ADC interrupt flag is the ADIF bit in the PIR1 register. The ADC interrupt enable is the ADIE bit in the PIE1 register. The ADIF bit must be cleared in software.

- **Note 1:** The ADIF bit is set at the completion of every conversion, regardless of whether or not the ADC interrupt is enabled.
  - **2:** The ADC operates during Sleep only when the FRC oscillator is selected.

This interrupt can be generated while the device is operating or while in Sleep. If the device is in Sleep, the interrupt will wake-up the device. Upon waking from Sleep, the next instruction following the SLEEP instruction is always executed. If the user is attempting to wake-up from Sleep and resume in-line code execution, the GIE and PEIE bits of the INTCON register must be disabled. If the GIE and PEIE bits of the INT-CON register are enabled, execution will switch to the Interrupt Service Routine.

Please refer to **Section 9.1.5** "Interrupts" for more information.

#### 9.2 ADC Operation

#### 9.2.1 STARTING A CONVERSION

To enable the ADC module, the ADON bit of the ADCON0 register must be set to a '1'. Setting the GO/ DONE bit of the ADCON0 register to a '1' will start the Analog-to-Digital conversion.

Note: The GO/DONE bit should not be set in the same instruction that turns on the ADC. Refer to Section 9.2.6 "A/D Conversion Procedure".

#### 9.2.2 COMPLETION OF A CONVERSION

When the conversion is complete, the ADC module will:

- Clear the GO/DONE bit
- Set the ADIF Interrupt Flag bit
- Update the ADRES register with new conversion result

#### 9.2.3 TERMINATING A CONVERSION

If a conversion must be terminated before completion, the GO/DONE bit can be cleared in software. The ADRES register will be updated with the partially complete Analog-to-Digital conversion sample. Incomplete bits will match the last bit converted.

Note:	A device Reset forces all registers to their									
	Reset state. Thus, the ADC module is									
	turned off and any pending conversion is									
	terminated.									

#### 9.2.4 ADC OPERATION DURING SLEEP

The ADC module can operate during Sleep. This requires the ADC clock source to be set to the FRC option. When the FRC clock source is selected, the ADC waits one additional instruction before starting the conversion. This allows the SLEEP instruction to be executed, which can reduce system noise during the conversion. If the ADC interrupt is enabled, the device will wake-up from Sleep when the conversion completes. If the ADC interrupt is disabled, the ADC module is turned off after the conversion completes, although the ADON bit remains set.

When the ADC clock source is something other than FRC, a SLEEP instruction causes the present conversion to be aborted and the ADC module is turned off, although the ADON bit remains set.

#### 9.2.5 SPECIAL EVENT TRIGGER

The Special Event Trigger of the CCP module allows periodic ADC measurements without software intervention. When this trigger occurs, the GO/DONE bit is set by hardware and the Timer1 counter resets to zero.

Using the Special Event Trigger does not assure proper ADC timing. It is the user's responsibility to ensure that the ADC timing requirements are met.

Refer to Section 15.0 "Capture/Compare/PWM (CCP) Module" for more information.

#### 9.3 A/D Acquisition Requirements

For the ADC to meet its specified accuracy, the charge holding capacitor (CHOLD) must be allowed to fully charge to the input channel voltage level. The Analog Input model is shown in Figure 9-3. The source impedance (Rs) and the internal sampling switch (Rss) impedance directly affect the time required to charge the capacitor CHOLD. The sampling switch (Rss) impedance varies over the device voltage (VDD), refer to Figure 9-3. The maximum recommended impedance for analog sources is 10 k $\Omega$ . As the source

impedance is decreased, the acquisition time may be decreased. After the analog input channel is selected (or changed), an A/D acquisition must be done before the conversion can be started. To calculate the minimum acquisition time, Equation 9-1 may be used. This equation assumes that 1/2 LSb error is used (256 steps for the ADC). The 1/2 LSb error is the maximum error allowed for the ADC to meet its specified resolution.

#### EQUATION 9-1: ACQUISITION TIME EXAMPLE

Assumptions: Temperature = 
$$50^{\circ}C$$
 and external impedance of  $10k\Omega 5.0V VDD$   
 $TACQ = Amplifier Settling Time + Hold Capacitor Charging Time + Temperature Coefficient$   
 $= TAMP + TC + TCOFF$   
 $= 2\mu s + TC + [(Temperature - 25^{\circ}C)(0.05\mu s/^{\circ}C)]$   
The value for TC can be approximated with the following equations:  
 $V_{APPLIED}\left(1 - \frac{1}{1-1}\right) = V_{CHOLD}$  :[11 VCHOLD charged to within 1/2 lsb

$$(2^{n+1}) - 1'$$

$$V_{APPLIED}\left(1 - e^{\frac{-TC}{RC}}\right) = V_{CHOLD}$$
;[2] V\_{CHOLD charge response to V\_{APPLIED}}

$$V_{APPLIED}\left(1-e^{\frac{-ic}{RC}}\right) = V_{APPLIED}\left(1-\frac{1}{(2^{n+1})-l}\right) \quad (combining [1] and [2])$$

*Note:* Where n = number of bits of the ADC.

Solving for TC:

$$T_{C} = -C_{HOLD}(R_{IC} + R_{SS} + R_{S}) \ln(1/511)$$
  
=  $-10pF(1k\Omega + 7k\Omega + 10k\Omega) \ln(0.001957)$   
=  $1.12\mu s$   
$$c_{O} = 2M_{S} + 1.12M_{S} + [(50^{\circ}C - 25^{\circ}C)(0.05M_{S}/^{\circ}C)]$$

Therefore:

$$TACQ = 2MS + 1.12MS + [(50°C-25°C)(0.05MS/°C)]$$
  
= 4.42MS

**Note 1:** The reference voltage (VREF) has no effect on the equation, since it cancels itself out.

- 2: The charge holding capacitor (CHOLD) is not discharged after each conversion.
- **3:** The maximum recommended impedance for analog sources is  $10 \text{ k}\Omega$ . This is required to meet the pin leakage specification.

#### 15.3.4 PWM RESOLUTION

The resolution determines the number of available duty cycles for a given period. For example, a 10-bit resolution will result in 1024 discrete duty cycles, whereas an 8-bit resolution will result in 256 discrete duty cycles.

The maximum PWM resolution is ten bits when PR2 is 255. The resolution is a function of the PR2 register value as shown by Equation 15-4.

#### EQUATION 15-4: PWM RESOLUTION

Resolution = 
$$\frac{\log[4(PR2+1)]}{\log(2)}$$
 bits

Note: If the pulse-width value is greater than the period, the assigned PWM pin(s) will remain unchanged.

#### TABLE 15-5: EXAMPLE PWM FREQUENCIES AND RESOLUTIONS (Fosc = 20 MHz)

PWM Frequency	1.22 kHz 4.88 kHz 19.53		19.53 kHz	78.12 kHz	156.3 kHz	208.3 kHz
Timer Prescale (1, 4, 16)	16	4	1	1	1	1
PR2 Value	0xFF	0xFF	0xFF	0x3F	0x1F	0x17
Maximum Resolution (bits)	10	10	10	8	7	6.6

#### TABLE 15-6: EXAMPLE PWM FREQUENCIES AND RESOLUTIONS (Fosc = 8 MHz)

PWM Frequency	1.22 kHz 4.90 kHz 1		19.61 kHz	76.92 kHz	153.85 kHz	200.0 kHz
Timer Prescale (1, 4, 16)	16	4	1	1	1	1
PR2 Value	0x65	0x65	0x65	0x19	0x0C	0x09
Maximum Resolution (bits)	8	8	8	6	5	5

#### 15.3.5 OPERATION IN SLEEP MODE

In Sleep mode, the TMR2 register will not increment and the state of the module will not change. If the CCPx pin is driving a value, it will continue to drive that value. When the device wakes up, TMR2 will continue from its previous state.

#### 15.3.6 CHANGES IN SYSTEM CLOCK FREQUENCY

The PWM frequency is derived from the system clock frequency (Fosc). Any changes in the system clock frequency will result in changes to the PWM frequency. Refer to **Section 7.0** "**Oscillator Module**" for additional details.

#### 15.3.7 EFFECTS OF RESET

Any Reset will force all ports to Input mode and the CCP registers to their Reset states.

#### 15.3.8 SETUP FOR PWM OPERATION

The following steps should be taken when configuring the CCP module for PWM operation:

- 1. Disable the PWM pin (CCPx) output driver(s) by setting the associated TRIS bit(s).
- 2. Load the PR2 register with the PWM period value.
- Configure the CCP module for the PWM mode by loading the CCPxCON register with the appropriate values.

- Load the CCPRxL register and the DCxBx bits of the CCPxCON register, with the PWM duty cycle value.
- 5. Configure and start Timer2:
  - Clear the TMR2IF interrupt flag bit of the PIR1 register. See Note below.
  - Configure the T2CKPS bits of the T2CON register with the Timer2 prescale value.
  - Enable Timer2 by setting the TMR2ON bit of the T2CON register.
- 6. Enable PWM output pin:
  - Wait until Timer2 overflows, TMR2IF bit of the PIR1 register is set. See Note below.
  - Enable the PWM pin (CCPx) output driver(s) by clearing the associated TRIS bit(s).
  - **Note:** In order to send a complete duty cycle and period on the first PWM output, the above steps must be included in the setup sequence. If it is not critical to start with a complete PWM signal on the first output, then step 6 may be ignored.

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R-0	R-0	R-x
SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D
bit 7			-				bit 0
Legend:							
R = Reada	ble bit	W = Writable	bit	U = Unimple	mented bit, read	d as '0'	
-n = Value	at POR	'1' = Bit is set		'0' = Bit is cle	eared	x = Bit is unkne	own
bit 7	SPEN: Serial	l Port Enable bi	t(1)				
	1 = Serial po	ort enabled (cor	figures RX/D	T and TX/CK p	oins as serial po	ort pins)	
h:4.0	0 = Serial pc	ort disabled (hel	id in Reset)				
DIT 6	1 - Selects	eceive Enable c	DIT				
	1 =  Selects $3 = 0 = $ Selects $3 = 0 = 0 = 0$	B-bit reception					
bit 5	SREN: Single	e Receive Enat	ole bit				
	Asynchronou	<u>is mode</u> :					
	Don't care						
	Synchronous	mode – Maste	<u>r</u> :				
	1 = Enables	single receive					
	This bit is cle	ared after recei	otion is compl	ete.			
	Synchronous	mode – Slave:					
	Don't care						
bit 4	CREN: Conti	nuous Receive	Enable bit				
	Asynchronou	is mode:					
	1 = Enables 0 = Disables	receiver					
	Synchronous	mode:					
	1 = Enables	continuous rec	eive until enal	ole bit CREN is	s cleared (CRE	N overrides SRE	N)
	0 = Disables	continuous rec	ceive				
bit 3	ADDEN: Add	Iress Detect En	able bit $XO = 1$				
	1 – Enables	address detect	ion enable in	terrunt and loa	d the receive h	uffer when RSR.	<85 is set
	0 = Disables	address detec	tion, all bytes	are received a	and ninth bit car	be used as pari	ity bit
	<u>Asynchronou</u>	is mode 8-bit (F	<u>RX9 = 0)</u> :				
	Don't care	mode					
	<u>Synchronous</u> Must be set t	<u>nioue</u> .					
bit 2	FFRR: Frami	ing Error bit					
Sit L	1 = Framing	error (can be u	pdated by rea	iding RCREG	register and rec	eive next valid b	ovte)
	0 = No frami	ng error	. ,	0	C		
bit 1	OERR: Over	run Error bit					
	1 = Overrun	error (can be c	leared by clea	ring bit CREN	)		
hit O	0 = NO OVER	un error	Dete				
DILU	This can be a	uii ui Received	Dala for a parity bit	and must be	calculated by u	ser firmware	
		aduress/uala Dil					
Note 1:	The AUSART m TRISx = $1$ .	nodule automat	tically change	es the pin fro	m tri-state to	drive as neede	d. Configure

#### REGISTER 16-2: RCSTA: RECEIVE STATUS AND CONTROL REGISTER

	SYNC = 0, BRGH = 1											
BAUD	Fosc = 8.000 MHz			Fosc = 4.000 MHz			Fosc = 3.6864 MHz			Fosc = 1.000 MHz		
RATE	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)
300	_	_	—				_		_	300	0.16	207
1200	—	—	—	1202	0.16	207	1200	0.00	191	1202	0.16	51
2400	2404	0.16	207	2404	0.16	103	2400	0.00	95	2404	0.16	25
9600	9615	0.16	51	9615	0.16	25	9600	0.00	23	—	_	—
10417	10417	0.00	47	10417	0.00	23	10473	0.53	21	10417	0.00	5
19.2k	19231	0.16	25	19.23k	0.16	12	19.2k	0.00	11	—	_	_
57.6k	55556	-3.55	8	—	—	—	57.60k	0.00	3	—	—	—
115.2k	—	—	_	—	_	—	115.2k	0.00	1	_	_	—

#### TABLE 16-5: BAUD RATES FOR ASYNCHRONOUS MODES

FIGURE 16-8:	SYNCHRONOUS RECEPTION (MASTER MODE, SREN)
RX/DT pin	bit 0         bit 2         bit 3         bit 4         bit 5         bit 6         bit 7
TX/CK pin	
Write to bit SREN	
SREN bit	
CREN bit	ʻ0'
RCIF bit (Interrupt) ———	
Read RCREG	
Note: Timing d	iagram demonstrates Synchronous Master mode with bit SREN = $1$ and bit BRGH = $0$ .

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
INTCON	GIE	PEIE	TOIE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 000x
PIE1	TMR1GIE	ADIE	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	0000 0000
PIR1	TMR1GIF	ADIF	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 0000	0000 0000
RCREG	AUSART R	eceive Data	a Register						0000 0000	0000 0000
RCSTA	SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D	0000 000X	0000 000x
TRISC	TRISC7	TRISC6	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0	1111 1111	1111 1111
TXSTA	CSRC	TX9	TXEN	SYNC	—	BRGH	TRMT	TX9D	0000 -010	0000 -010

#### TABLE 16-7: REGISTERS ASSOCIATED WITH SYNCHRONOUS MASTER RECEPTION

Legend: x = unknown, - = unimplemented read as '0'. Shaded cells are not used for Synchronous Master Reception.

Mnemo	onic,	Description	Cycles		14-Bit	Opcode	•	Status	Notoo
Opera	nds	Description	Cycles	MSb			LSb	Affected	Notes
		BYTE-ORIENTED FILE REGIS	TER OPE	RATIO	NS				
ADDWF	f, d	Add W and f	1	00	0111	dfff	ffff	C, DC, Z	1, 2
ANDWF	f, d	AND W with f	1	00	0101	dfff	ffff	Z	1, 2
CLRF	f	Clear f	1	00	0001	lfff	ffff	Z	2
CLRW	-	Clear W	1	00	0001	0xxx	xxxx	Z	
COMF	f, d	Complement f	1	00	1001	dfff	ffff	Z	1, 2
DECF	f, d	Decrement f	1	00	0011	dfff	ffff	Z	1, 2
DECFSZ	f, d	Decrement f, Skip if 0	1 <b>(2)</b>	00	1011	dfff	ffff		1, 2, 3
INCF	f, d	Increment f	1	00	1010	dfff	ffff	Z	1, 2
INCFSZ	f, d	Increment f, Skip if 0	1 <b>(2)</b>	00	1111	dfff	ffff		1, 2, 3
IORWF	f, d	Inclusive OR W with f	1	00	0100	dfff	ffff	Z	1, 2
MOVF	f, d	Move f	1	00	1000	dfff	ffff	Z	1, 2
MOVWF	f	Move W to f	1	00	0000	lfff	ffff		
NOP	-	No Operation	1	00	0000	0xx0	0000		
RLF	f, d	Rotate Left f through Carry	1	00	1101	dfff	ffff	С	1, 2
RRF	f, d	Rotate Right f through Carry	1	00	1100	dfff	ffff	С	1, 2
SUBWF	f, d	Subtract W from f	1	00	0010	dfff	ffff	C, DC, Z	1, 2
SWAPF	f, d	Swap nibbles in f	1	00	1110	dfff	ffff		1, 2
XORWF	f, d	Exclusive OR W with f	1	00	0110	dfff	ffff	Z	1, 2
		BIT-ORIENTED FILE REGIST		ATION	IS				•
BCF	f. b	Bit Clear f	1	01	00bb	bfff	ffff		1.2
BSF	f, b	Bit Set f	1	01	01bb	bfff	ffff		1.2
BTFSC	f. b	Bit Test f. Skip if Clear	1 (2)	01	10bb	bfff	ffff		3
BTFSS	f. b	Bit Test f. Skip if Set	1 (2)	01	11bb	bfff	ffff		3
	, -	LITERAL AND CONTROL	OPERAT	IONS					
ADDLW	k	Add literal and W	1	11	111x	kkkk	kkkk	C, DC, Z	
ANDLW	k	AND literal with W	1	11	1001	kkkk	kkkk	Z	
CALL	k	Call Subroutine	2	10	0kkk	kkkk	kkkk		
CLRWDT	-	Clear Watchdog Timer	1	00	0000	0110	0100	TO, PD	
GOTO	k	Go to address	2	10	1kkk	kkkk	kkkk		
IORLW	k	Inclusive OR literal with W	1	11	1000	kkkk	kkkk	Z	
MOVLW	k	Move literal to W	1	11	00xx	kkkk	kkkk		
RETFIE	-	Return from interrupt	2	00	0000	0000	1001		
RETLW	k	Return with literal in W	2	11	01xx	kkkk	kkkk		
RETURN	-	Return from Subroutine	2	00	0000	0000	1000		
SLEEP	-	Go into Standby mode	1	00	0000	0110	0011	TO, PD	
SUBLW	k	Subtract W from literal	1	11	110x	kkkk	kkkk	C, DC, Z	
XORLW	k	Exclusive OR literal with W	1	11	1010	kkkk	kkkk	Z	

#### TABLE 21-2: PIC16(L)F722/3/4/6/7 INSTRUCTION SET

**Note 1:** When an I/O register is modified as a function of itself (e.g., MOVF PORTA, 1), the value used will be that value present on the pins themselves. For example, if the data latch is '1' for a pin configured as input and is driven low by an external device, the data will be written back with a '0'.

2: If this instruction is executed on the TMR0 register (and where applicable, d = 1), the prescaler will be cleared if assigned to the Timer0 module.

**3:** If the Program Counter (PC) is modified, or a conditional test is true, the instruction requires two cycles. The second cycle is executed as a NOP.

#### 22.11 Demonstration/Development Boards, Evaluation Kits, and Starter Kits

A wide variety of demonstration, development and evaluation boards for various PIC MCUs and dsPIC DSCs allows quick application development on fully functional systems. Most boards include prototyping areas for adding custom circuitry and provide application firmware and source code for examination and modification.

The boards support a variety of features, including LEDs, temperature sensors, switches, speakers, RS-232 interfaces, LCD displays, potentiometers and additional EEPROM memory.

The demonstration and development boards can be used in teaching environments, for prototyping custom circuits and for learning about various microcontroller applications.

In addition to the PICDEM<sup>™</sup> and dsPICDEM<sup>™</sup> demonstration/development board series of circuits, Microchip has a line of evaluation kits and demonstration software for analog filter design, KEELOQ<sup>®</sup> security ICs, CAN, IrDA<sup>®</sup>, PowerSmart battery management, SEEVAL<sup>®</sup> evaluation system, Sigma-Delta ADC, flow rate sensing, plus many more.

Also available are starter kits that contain everything needed to experience the specified device. This usually includes a single application and debug capability, all on one board.

Check the Microchip web page (www.microchip.com) for the complete list of demonstration, development and evaluation kits.

## 22.12 Third-Party Development Tools

Microchip also offers a great collection of tools from third-party vendors. These tools are carefully selected to offer good value and unique functionality.

- Device Programmers and Gang Programmers from companies, such as SoftLog and CCS
- Software Tools from companies, such as Gimpel and Trace Systems
- Protocol Analyzers from companies, such as Saleae and Total Phase
- Demonstration Boards from companies, such as MikroElektronika, Digilent<sup>®</sup> and Olimex
- Embedded Ethernet Solutions from companies, such as EZ Web Lynx, WIZnet and IPLogika<sup>®</sup>

## 23.7 AC Characteristics: PIC16F72X-I/E



#### FIGURE 23-3: CLOCK TIMING













Note 1: If the A/D clock source is selected as RC, a time of TcY is added before the A/D clock starts. This allows the SLEEP instruction to be executed.





#### TABLE 23-9: USART SYNCHRONOUS TRANSMISSION REQUIREMENTS

Standard Operating	Standard Operating Conditions (unless otherwise stated)Operating Temperature $-40^{\circ}C \le TA \le +125^{\circ}C$											
Param. No.	Symbol	Characteristic		Min.	Max.	Units	Conditions					
US120	ТскH2dtV	SYNC XMIT (Master and Slave)	3.0-5.5V	—	80	ns						
		Clock high to data-out valid	1.8-5.5V	—	100	ns						
US121	TCKRF	Clock out rise time and fall time	3.0-5.5V	—	45	ns						
		(Master mode)	1.8-5.5V	—	50	ns						
US122	TDTRF	Data-out rise time and fall time	3.0-5.5V	_	45	ns						
			1.8-5.5V	_	50	ns						

#### FIGURE 23-15: USART SYNCHRONOUS RECEIVE (MASTER/SLAVE) TIMING



10

15

ns

ns

#### TABLE 23-10: USART SYNCHRONOUS RECEIVE REQUIREMENTS

Data-hold before  $CK \downarrow (DT hold time)$ 

Data-hold after  $CK \downarrow (DT hold time)$ 

# Standard Operating Conditions (unless otherwise stated) Operating Temperature -40°C ≤ TA ≤ +125°C Param. Symbol Characteristic Min. Max. Units Conditions US125 TDTV2CKL SYNC RCV (Master and Slave) Image: Condition state s

US126

TCKL2DTL

$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	Conditions
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	
$ \begin{array}{ c c c c c c c } \hline SP72^{\star} & TscL & SCK input low time (Slave mode) & Tcr + 20 & - & - & ns \\ \hline SP73^{\star} & TblV2scH, \\ TblV2scL & Setup time of SDI data input to SCK edge & 100 & - & - & ns \\ \hline SP74^{\star} & TscH2blL, \\ TscL2blL & Hold time of SDI data input to SCK edge & 100 & - & - & ns \\ \hline SP75^{\star} & TboR & SDO data output rise time & 3.0-5.5V & - & 10 & 25 & ns \\ \hline SP76^{\star} & TboF & SDO data output fall time & - & 10 & 25 & ns \\ \hline SP77^{\star} & TsSH2boZ & \overline{SS}^{\uparrow} to SDO output high-impedance & 10 & - & 50 & ns \\ \hline SP78^{\star} & TscR & SCK output rise time & 3.0-5.5V & - & 10 & 25 & ns \\ \hline \end{array} $	
$ \begin{array}{ c c c c c c c c c } & & & & & & & & & & & & & & & & & & &$	
$ \begin{array}{ c c c c c c c c c c c c c c c c c c c$	
$ \begin{array}{ c c c c c c c c } & SP75^{*} & TDOR & SDO data output rise time & 3.0-5.5V & & 10 & 25 & ns & \hline \\ \hline 1.8-5.5V & & 25 & 50 & ns & \hline \\ SP76^{*} & TDOF & SDO data output fall time & & 10 & 25 & ns & \hline \\ SP77^{*} & TSSH2DOZ & \overline{SS}^{\uparrow} \ to \ SDO \ output \ high-impedance & 10 & & 50 & ns & \hline \\ SP78^{*} & TSCR & SCK \ output \ rise \ time & 3.0-5.5V & & 10 & 25 & ns & \hline \\ \end{array} $	
SP76*         TDOF         SDO data output fall time         1.8-5.5V         —         25         50         ns           SP76*         TDOF         SDO data output fall time         —         10         25         ns           SP77*         TssH2DOZ         SS↑ to SDO output high-impedance         10         —         50         ns           SP78*         TscR         SCK output rise time         3.0-5.5V         —         10         25         ns	
SP76*     TDoF     SDO data output fall time     —     10     25     ns       SP77*     TssH2DoZ     SS↑ to SDO output high-impedance     10     —     50     ns       SP78*     TscR     SCK output rise time     3.0-5.5V     —     10     25     ns	
SP77*     TssH2DoZ     SS↑ to SDO output high-impedance     10     —     50     ns       SP78*     TscR     SCK output rise time     3.0-5.5V     —     10     25     ns	
SP78*         TSCR         SCK output rise time         3.0-5.5V         —         10         25         ns	
(Master mode) 1.8-5.5V — 25 50 ns	
SP79*     TSCF     SCK output fall time (Master mode)     —     10     25     ns	
SP80*     TscH2DoV,     SDO data output valid after SCK     3.0-5.5V     —     —     50     ns	
TSCL2DOV edge 1.8-5.5V — — 145 ns	
SP81*     TDOV2scH, TDOV2scL     SDO data output setup to SCK edge     Tcy     —     —     ns	
SP82*TssL2DOVSDO data output valid after $\overline{SS}\downarrow$ edge——50ns	
SP83*     TscH2ssH, TscL2ssH     SS ↑ after SCK edge     1.5Tcy + 40     —     —     ns	

#### TABLE 23-11: SPI MODE REQUIREMENTS

These parameters are characterized but not tested.

Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance † only and are not tested.

#### FIGURE 23-20: I<sup>2</sup>C BUS START/STOP BITS TIMING



FIGURE 24-19: PIC16F722/3/4/6/7 MAXIMUM IDD vs. Fosc OVER VDD, INTOSC MODE, VCAP =  $0.1 \mu$ F







#### 25.2 Package Details

The following sections give the technical details of the packages.

#### 28-Lead Skinny Plastic Dual In-Line (SP) – 300 mil Body [SPDIP]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	Units		INCHES		
Dimensio	n Limits	MIN	NOM	MAX	
Number of Pins	Ν	28			
Pitch	е	.100 BSC			
Top to Seating Plane	А	-	-	.200	
Molded Package Thickness	A2	.120	.135	.150	
Base to Seating Plane	A1	.015	-	-	
Shoulder to Shoulder Width	E	.290	.310	.335	
Molded Package Width	E1	.240	.285	.295	
Overall Length	D	1.345	1.365	1.400	
Tip to Seating Plane	L	.110	.130	.150	
Lead Thickness	с	.008	.010	.015	
Upper Lead Width	b1	.040	.050	.070	
Lower Lead Width	b	.014	.018	.022	
Overall Row Spacing §	eB	_	_	.430	

#### Notes:

- 1. Pin 1 visual index feature may vary, but must be located within the hatched area.
- 2. § Significant Characteristic.
- 3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
- 4. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-070B